

# PBSS303PD

60 V, 3 A PNP low  $V_{CEsat}$  (BISS) transistor

Rev. 02 — 20 November 2009

Product data sheet

## 1. Product profile

### 1.1 General description

PNP low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) transistor in a SOT457 (SC-74) small Surface-Mounted Device (SMD) plastic package.

NPN complement: PBSS303ND.

### 1.2 Features

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability  $I_C$  and  $I_{CM}$
- High collector current gain ( $h_{FE}$ ) at high  $I_C$
- High efficiency due to less heat generation
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors

### 1.3 Applications

- High-voltage DC-to-DC conversion
- High-voltage MOSFET gate driving
- High-voltage motor control
- High-voltage power switches (e.g. motors, fans)
- Thin Film Transistor (TFT) backlight inverter
- Automotive applications

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	-60	V
$I_C$	collector current		[1]	-	-3	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	-6	A
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -2$ A; $I_B = -200$ mA	[2]	75	100	m $\Omega$

[1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

[2] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	collector		
2	collector		
3	base		
4	emitter		
5	collector		
6	collector		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS303PD	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PBSS303PD	AH

## 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-60	V
$V_{CEO}$	collector-emitter voltage	open base	-	-60	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$I_C$	collector current		[1] -	-1	A
			[2] -	-3	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-6	A
$I_B$	base current		-	-800	mA
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	-2	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1] -	360	mW
			[3] -	600	mW
			[4] -	750	mW
			[2] -	1.1	W
			[1][5] -	2.5	W
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

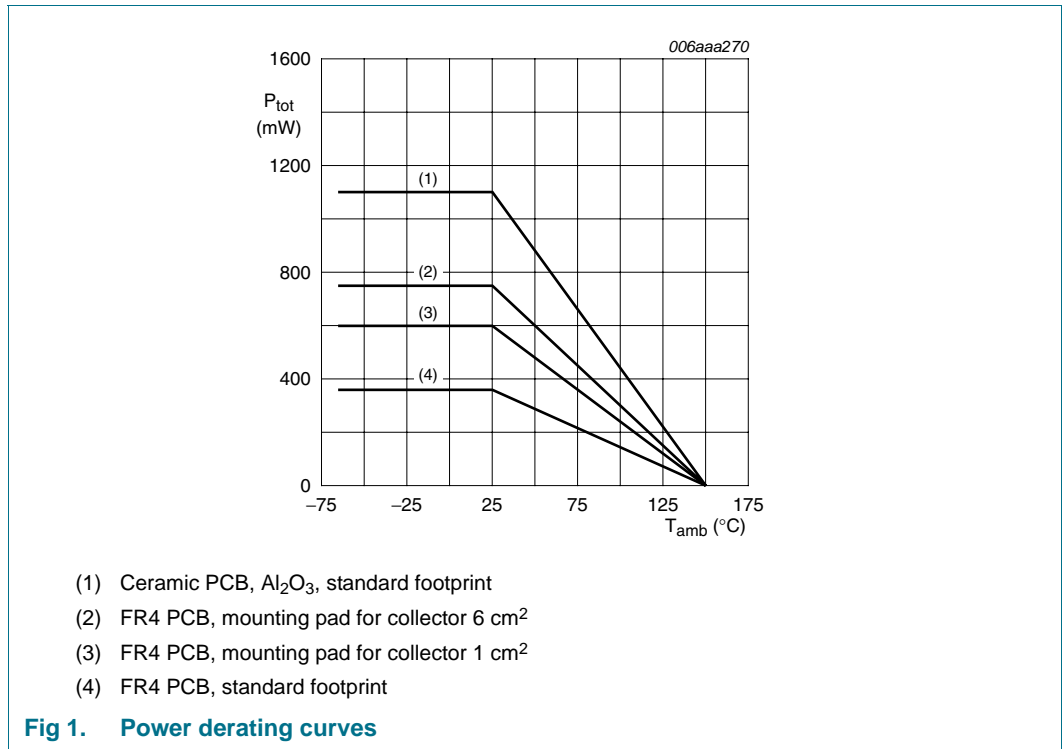
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

[5] Pulse test:  $t_p \leq 10$  ms;  $\delta \leq 10$  %.

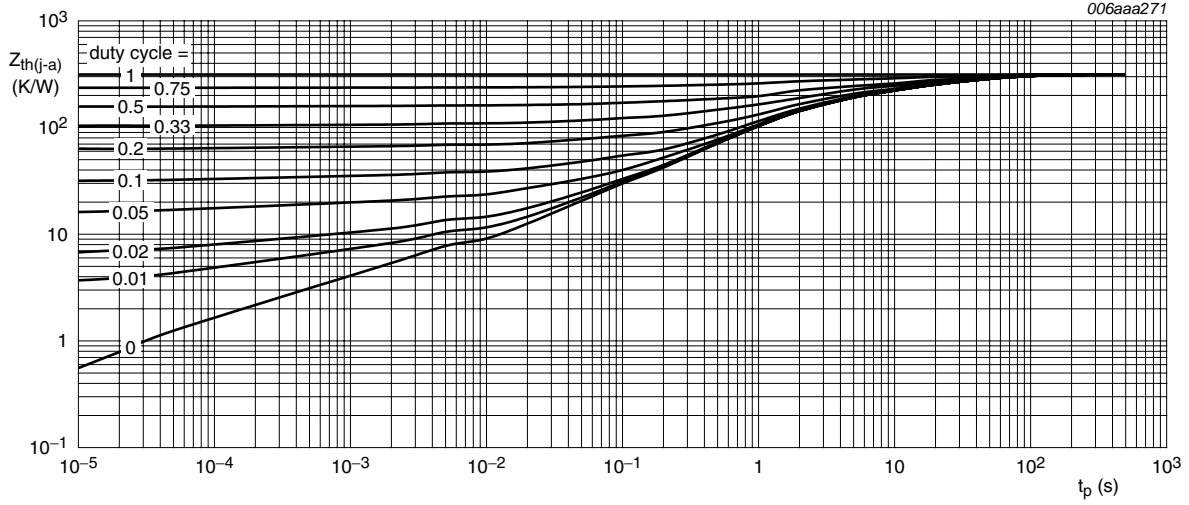


## 6. Thermal characteristics

**Table 6. Thermal characteristics**

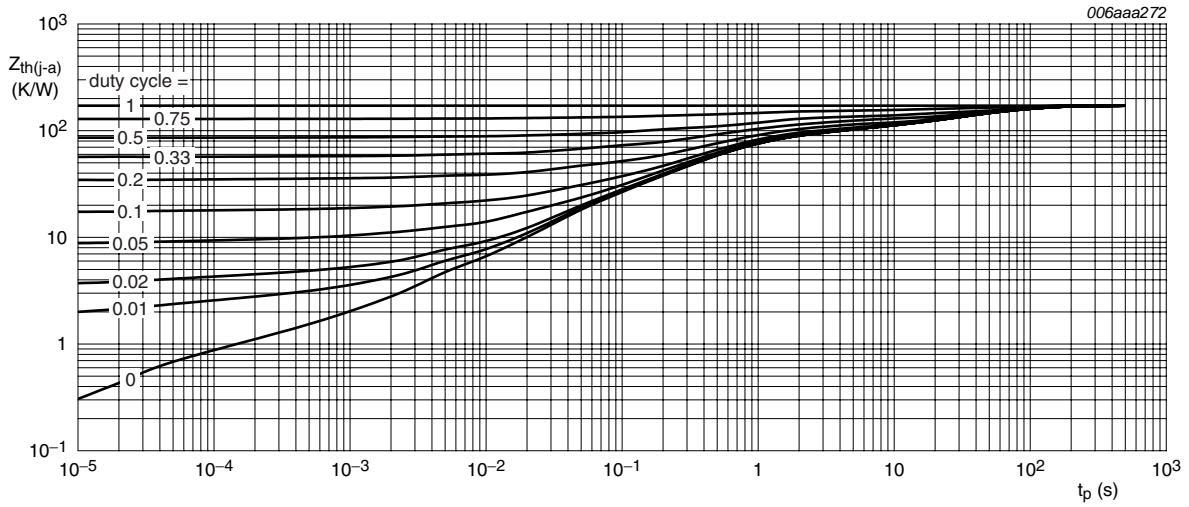
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1]	-	-	350	K/W
			[2]	-	-	208	K/W
			[3]	-	-	167	K/W
			[4]	-	-	113	K/W
			[1][5]	-	-	50	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		-	-	45	K/W	

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Pulse test: t<sub>p</sub> ≤ 10 ms; δ ≤ 10 %.



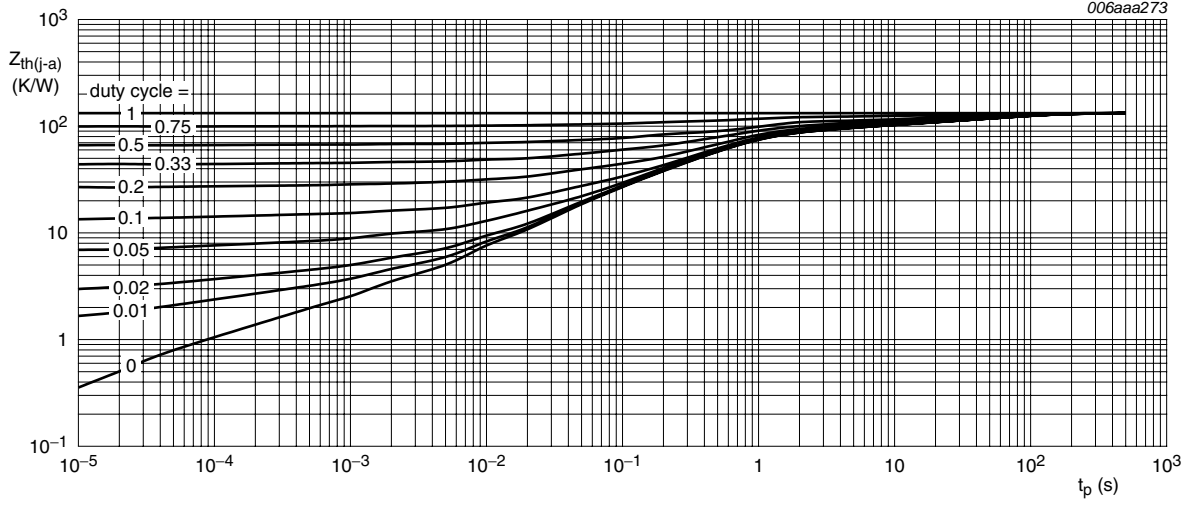
FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



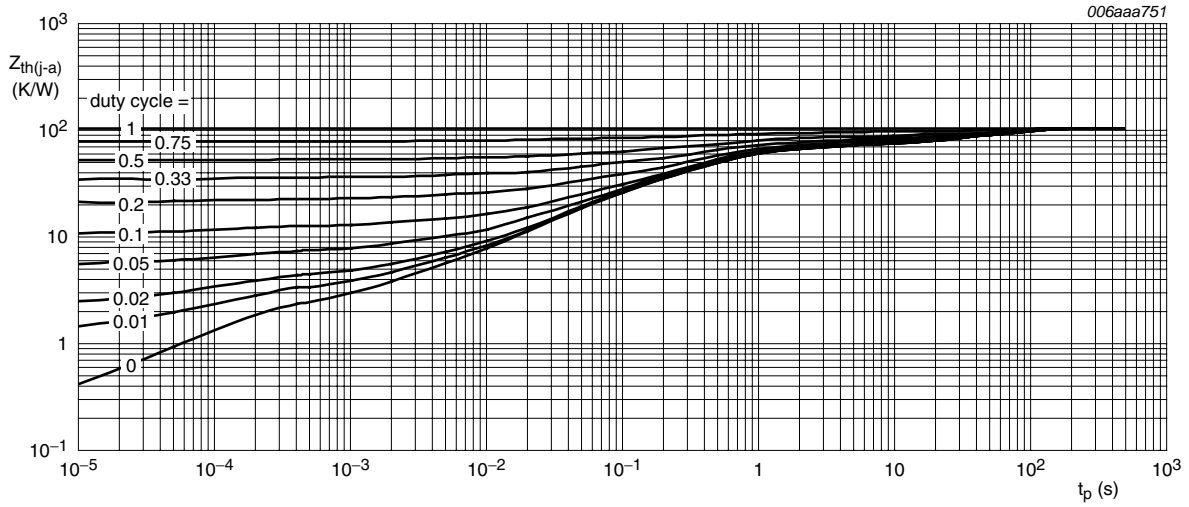
FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 7. Characteristics

**Table 7. Characteristics**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

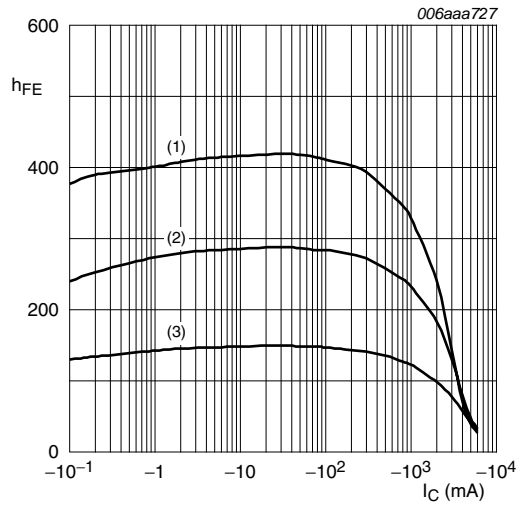
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -60\text{ V}; I_E = 0\text{ A}$	-	-	-100	nA
		$V_{CB} = -60\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	-50	$\mu\text{A}$
$I_{CES}$	collector-emitter cut-off current	$V_{CE} = -48\text{ V}; V_{BE} = 0\text{ V}$	-	-	-100	nA
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	-	-	-100	nA
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}; I_C = -500\text{ mA}$	180	265	-	
		$V_{CE} = -2\text{ V}; I_C = -1\text{ A}$	[1] 160	235	-	
		$V_{CE} = -2\text{ V}; I_C = -2\text{ A}$	[1] 130	185	-	
		$V_{CE} = -2\text{ V}; I_C = -3\text{ A}$	[1] 95	135	-	
		$V_{CE} = -2\text{ V}; I_C = -4\text{ A}$	[1] 60	80	-	
		$V_{CE} = -2\text{ V}; I_C = -5\text{ A}$	[1] 35	50	-	
		$V_{CE} = -2\text{ V}; I_C = -6\text{ A}$	[1] 20	30	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -500\text{ mA}; I_B = -50\text{ mA}$	-	-55	-70	mV
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	-	-100	-135	mV
		$I_C = -2\text{ A}; I_B = -200\text{ mA}$	[1] -	-150	-200	mV
		$I_C = -3\text{ A}; I_B = -150\text{ mA}$	[1] -	-275	-365	mV
		$I_C = -3\text{ A}; I_B = -300\text{ mA}$	[1] -	-210	-290	mV
		$I_C = -4\text{ A}; I_B = -400\text{ mA}$	[1] -	-285	-385	mV
		$I_C = -5\text{ A}; I_B = -500\text{ mA}$	[1] -	-375	-495	mV
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -2\text{ A}; I_B = -200\text{ mA}$	[1] -	75	100	$\text{m}\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -500\text{ mA}; I_B = -50\text{ mA}$	-	-0.78	-0.87	V
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	-	-0.80	-0.89	V
		$I_C = -1\text{ A}; I_B = -100\text{ mA}$	[1] -	-0.83	-0.92	V
		$I_C = -3\text{ A}; I_B = -150\text{ mA}$	[1] -	-0.92	-0.99	V
		$I_C = -3\text{ A}; I_B = -300\text{ mA}$	[1] -	-0.94	-1.02	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -2\text{ A}$	-	-0.80	-1.00	V

**Table 7. Characteristics ...continued**  
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_d$	delay time	$V_{CC} = -9.2\text{ V}$ ; $I_C = -2\text{ A}$ ;	-	13	-	ns
$t_r$	rise time	$I_{Bon} = -0.1\text{ A}$ ; $I_{Boff} = 0.1\text{ A}$	-	53	-	ns
$t_{on}$	turn-on time		-	66	-	ns
$t_s$	storage time		-	230	-	ns
$t_f$	fall time		-	76	-	ns
$t_{off}$	turn-off time		-	306	-	ns
$f_T$	transition frequency	$V_{CE} = -10\text{ V}$ ; $I_C = -100\text{ mA}$ ; $f = 100\text{ MHz}$	-	110	-	MHz
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}$ ; $I_E = I_e = 0\text{ A}$ ; $f = 1\text{ MHz}$	-	58	-	pF

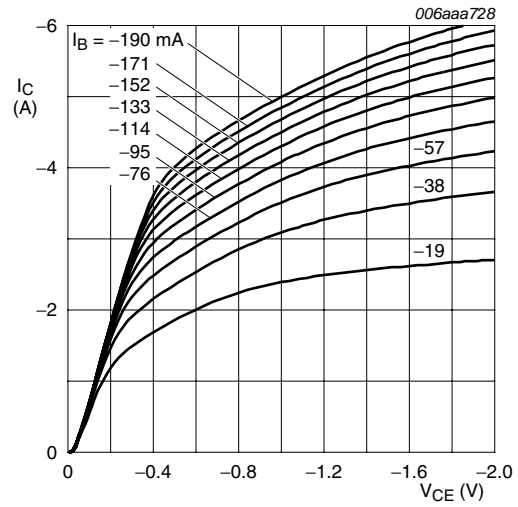
[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .





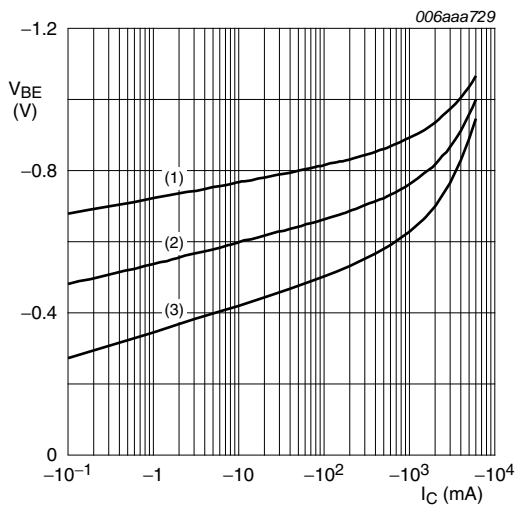
$V_{CE} = -2\text{ V}$   
 (1)  $T_{amb} = 100\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -55\text{ }^\circ\text{C}$

**Fig 6. DC current gain as a function of collector current; typical values**



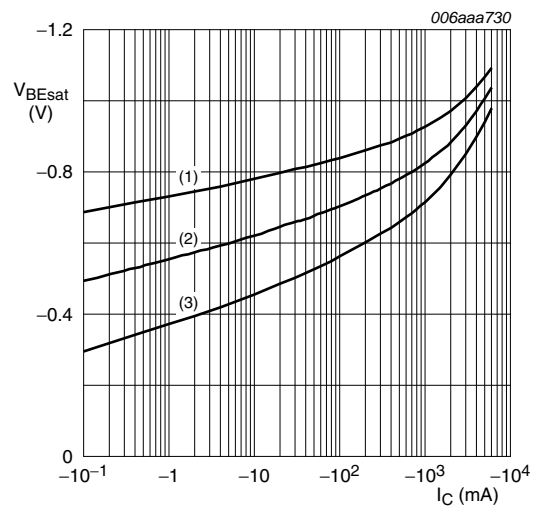
$T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 7. Collector current as a function of collector-emitter voltage; typical values**



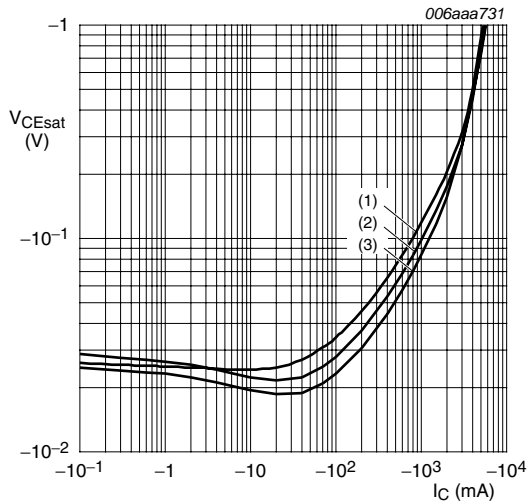
$V_{CE} = -2\text{ V}$   
 (1)  $T_{amb} = -55\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

**Fig 8. Base-emitter voltage as a function of collector current; typical values**



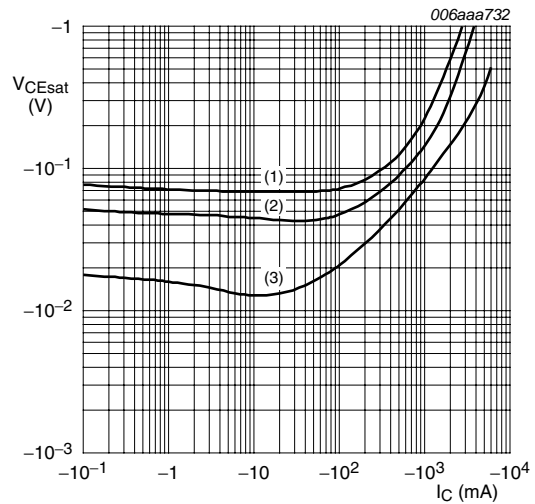
$I_C/I_B = 20$   
 (1)  $T_{amb} = -55\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

**Fig 9. Base-emitter saturation voltage as a function of collector current; typical values**



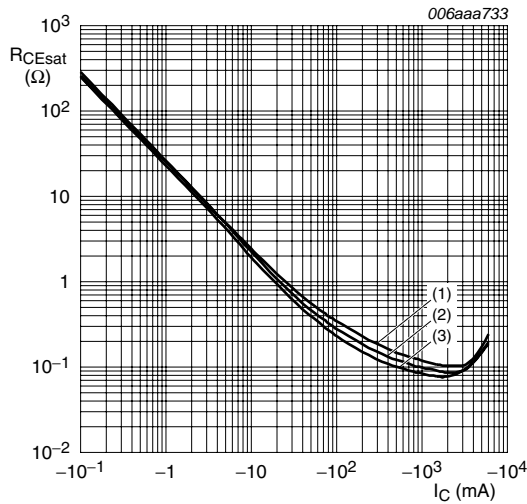
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values**



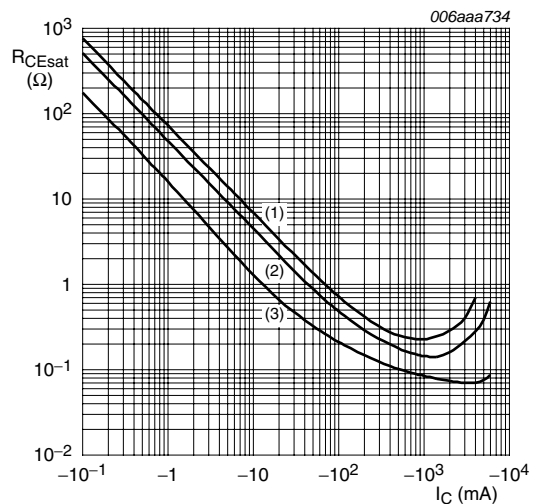
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 11. Collector-emitter saturation voltage as a function of collector current; typical values**



- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 12. Collector-emitter saturation resistance as a function of collector current; typical values**



- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 13. Collector-emitter saturation resistance as a function of collector current; typical values**

8. Test information

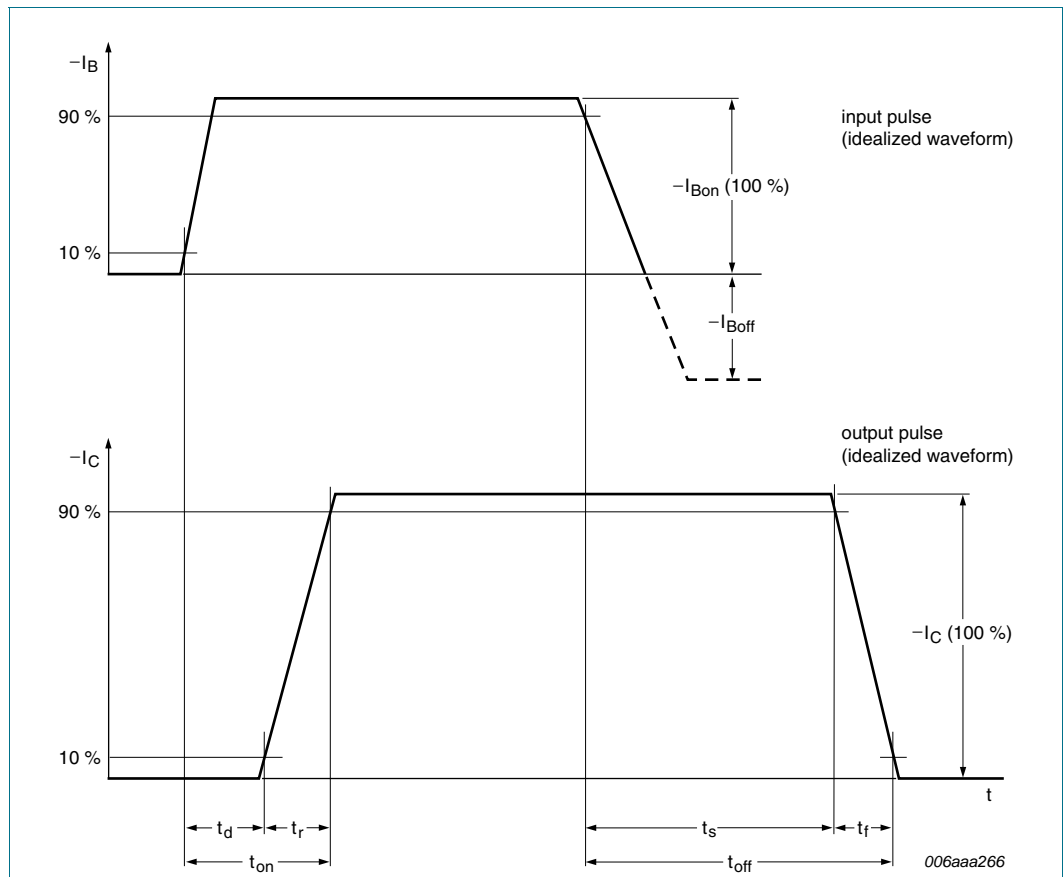
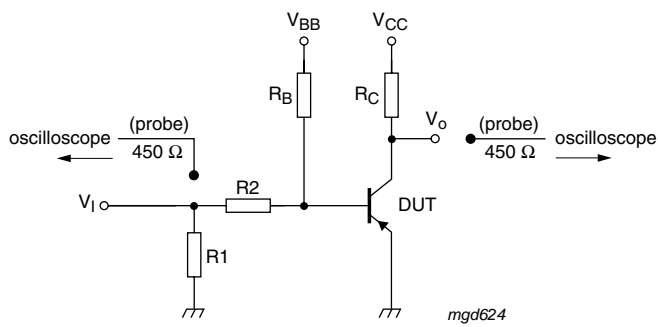


Fig 14. BISS transistor switching time definition



$V_{CC} = -9.2 \text{ V}$ ;  $I_C = -2 \text{ A}$ ;  $I_{Bon} = -0.1 \text{ A}$ ;  $I_{Boff} = 0.1 \text{ A}$

Fig 15. Test circuit for switching times

## 9. Package outline

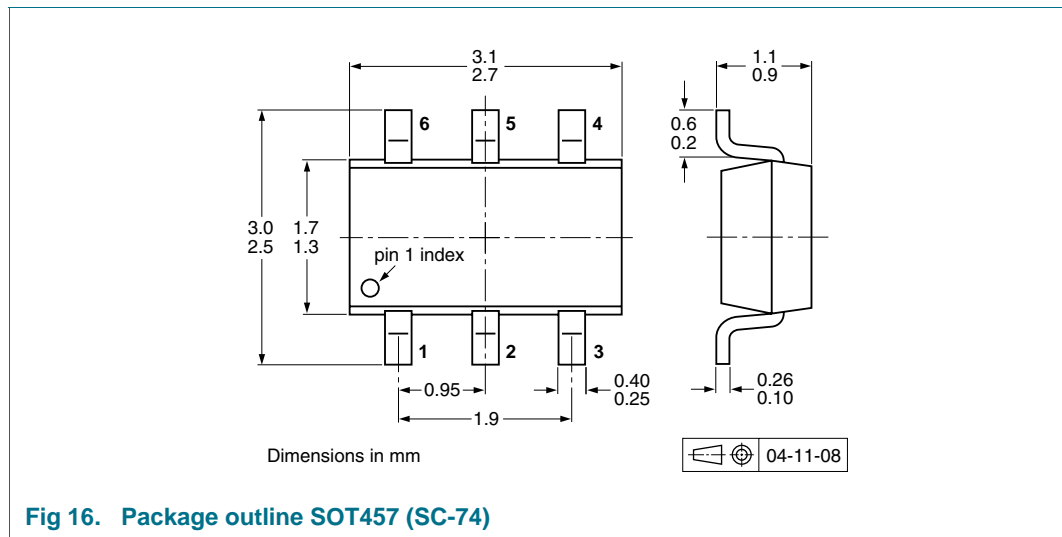


Fig 16. Package outline SOT457 (SC-74)

## 10. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

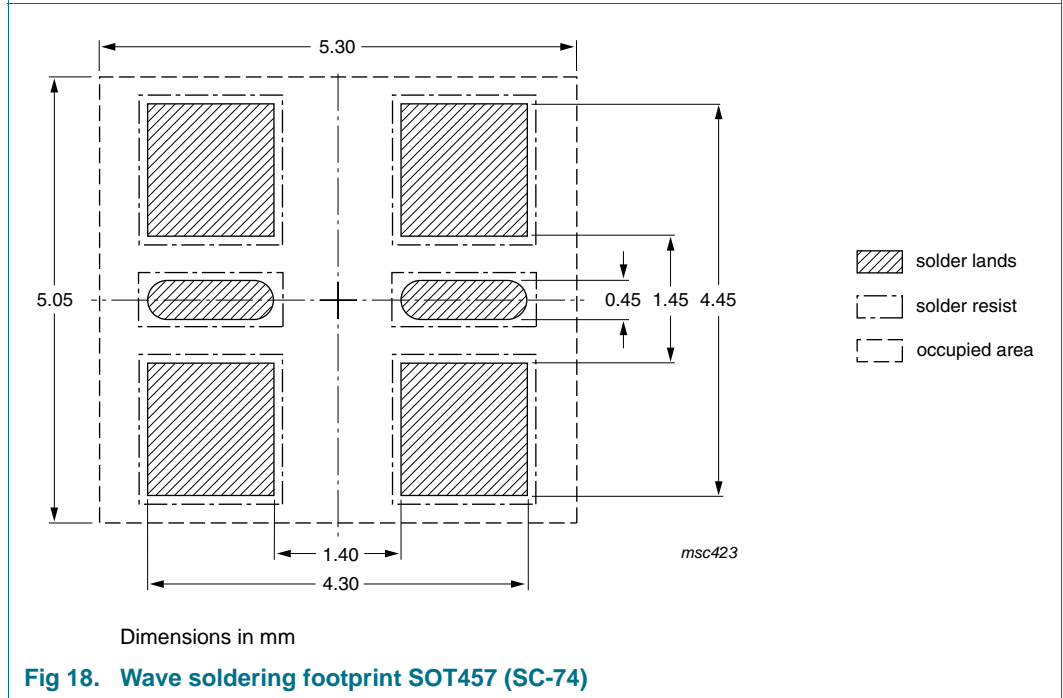
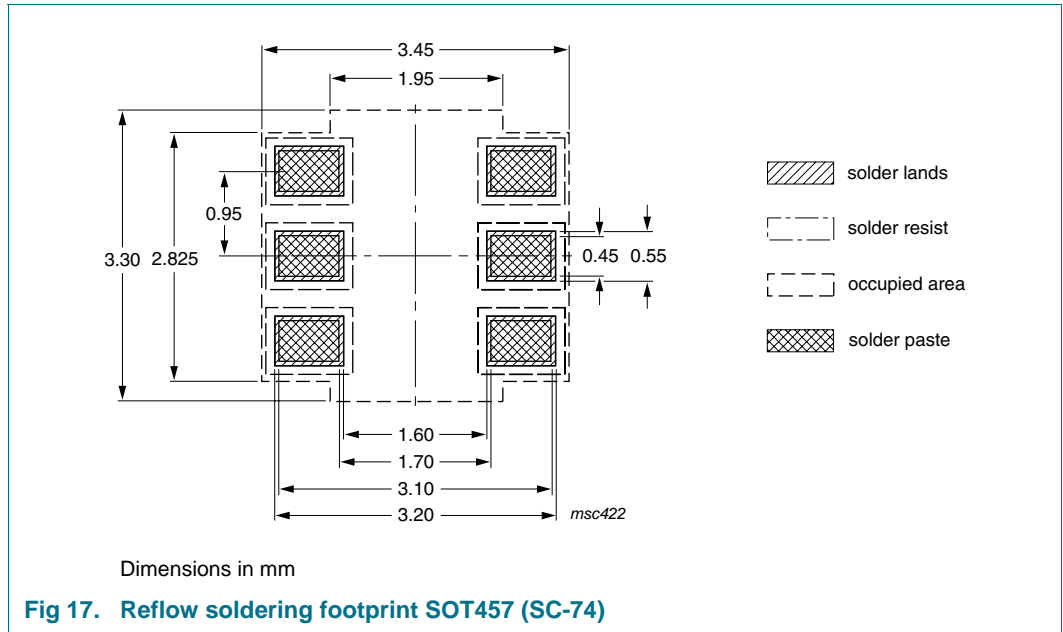
Type number	Package	Description	Packing quantity	
			3000	10000
PBSS303PD	SOT457	4 mm pitch, 8 mm tape and reel; T1 <sup>[2]</sup>	-115	-135
		4 mm pitch, 8 mm tape and reel; T2 <sup>[3]</sup>	-125	-165

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping

11. Soldering



## 12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS303PD_2	20091120	Product data sheet	-	PBSS303PD_1
Modifications:	<ul style="list-style-type: none"><li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li></ul>			
PBSS303PD_1	20060531	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 20 November 2009

Document identifier: PBSS303PD\_2